# **NNCI** Computation

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- To facilitate access to the modeling and simulation capabilities and expertise
- To promote and facilitate the development of new capabilities.
- To promote utilization of the computation resources.





#### Short Course on Electronic Device Modeling

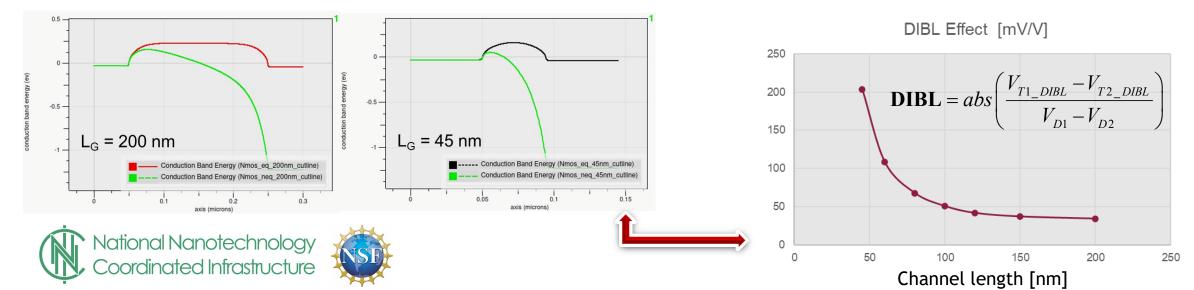
#### SDMS: Semiconductor Device Modeling and Simulation

By Dragica Vasileska

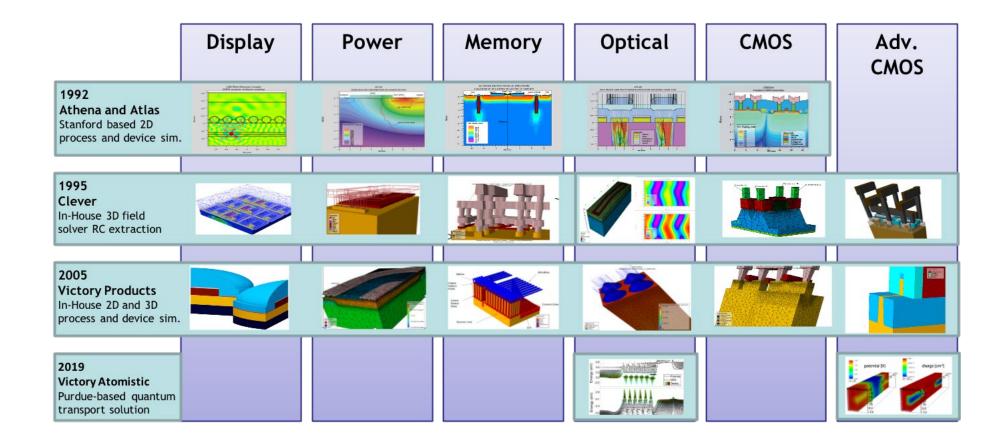
Electrical, Computer and Energy Engineering Arizona State University, Tempe AZ



#### https://nanohub.org/resources/37981



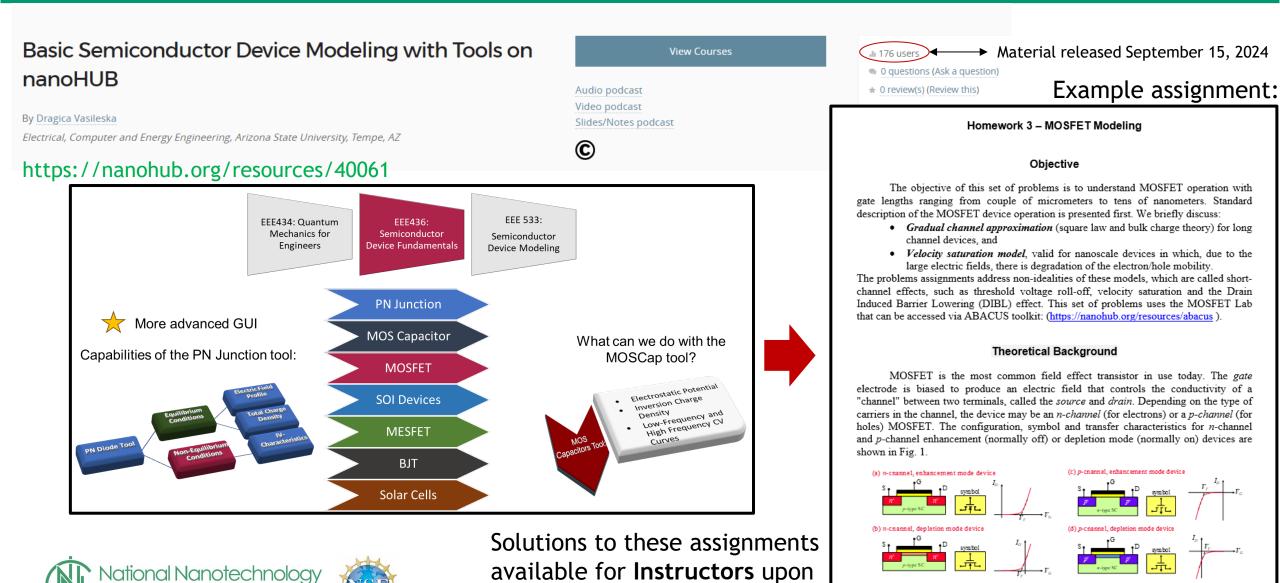
### Silvaco Modeling Tools on nanoHUB





#### Assignments are on NanoHUB – For Instructors

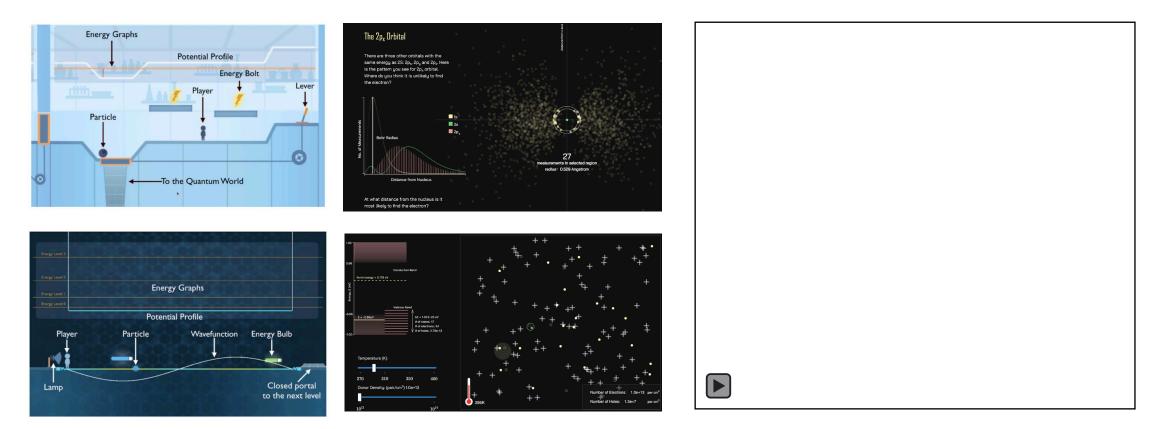
oordinated Infrastructure



request!

Figure 1. Cross-sectional diagrams, circuit symbols, and transfer characteristics of the four basic MOSFET configurations.

## Immersive Virtual Worlds for Experiential Learning of Microelectronics



Immersive Games from Classic to Quantum Worlds

> National Nanotechnology Coordinated Infrastructure

Interactive Visualizations from Hydrogen Atom to Carrier Statistics in Si Interactive Visualizations and Virtual Reality for Semiconductor Devices



https://learnqm.gatech.edu

#### Collaborative NSF Award



Program: Improving Undergraduate STEM Education (IUSE), Level 3

Title:Interactive Visualizations and Simulations for ConceptualUnderstanding in Quantum and Semiconductor Physics

#### Goals:

1) Enhance and Expand the educational tools for experiential learning of the semiconductor physics and devices.

2) Conduct large-scale evaluations of the tools with more than 350 students across 5 universities with very diverse populations.

3) Answer two major research Questions: To what extent can such tools change students' conceptions? and 2) How does the design of such tools affect students' conceptions?



#### Phase-Field Modeling of Domain Formation in FeFETs

- Phase-field model developed in COMSOL. Ο
- Coupled solution of 2-D Poisson's equation & Landau energy state Ο
  - Captures multi-domain texture in the ferroelectric layer. ۲
  - Impact of ferroelectric domain dynamics on the device's • electrostatics and transport including substantial changes in gate and source to drain tunneling
  - Device design guidelines derived for optimizing performance ۲ (ON/OFF ratio, switching speed, etc.)

10-

 $10^{-4}$ 

10-5

10-6

10

0.0

ds 10  $V_{ds} = 0.6$  \

0.2

0.4

 $V_{qs}(V)$ 

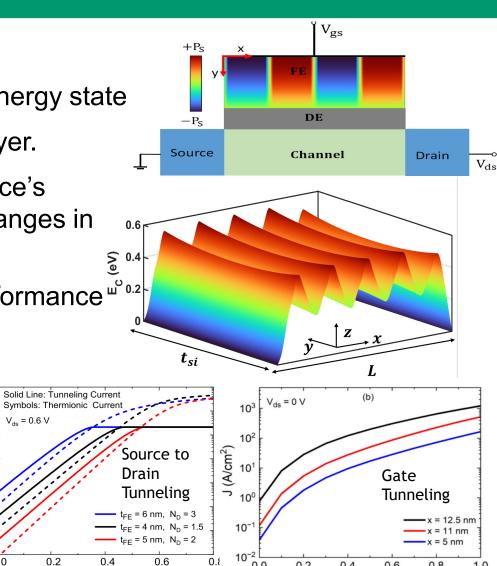
[1] N. Pandey, Y. S. Chauhan, L. F. Register, and S. K. Banerjee, "Dynamics of Domains and its Impact on Gate Tunneling in CMOS-Compatible FeFETs," IEEE Electron Device Letters, 2024, April 2024.

[2] N. Pandey, Y. S. Chauhan, L. F. Register and S. K. Banerjee, "Multi-Domain Dynamics E and Ultimate Scalability of CMOS-Compatible FeFETs," in IEEE Electron Device Letters.

[3] N. Pandey, Y. S. Chauhan, L. F. Register, and S. K. Banerjee, "Impact of Multi Domain on Ferroelectric Tunnel Junction Design Metrics," 82nd Device Research Conference (DRC), Washington DC, USA, June 2024.







0.0

0.2

0.4

0.6

 $V_{as}(V)$ 

0.8

1.0

### Phase-field Modeling of Multi-Domain Magnetic Tunnel Junctions

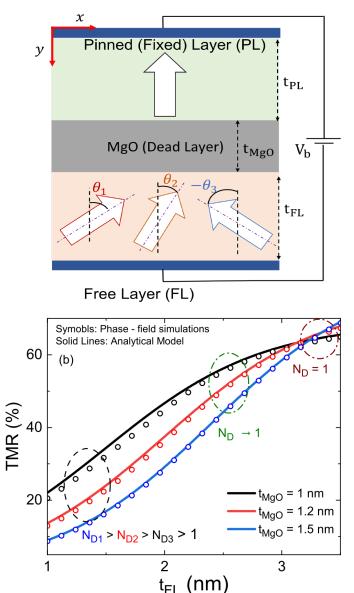
- Analytical model of magnetic tunnel junction derived by solving electrostatic Green's function
- Multi-domain impact on tunnel magnetic resistance (TMR) and switching speed analyzed.
- Basics of a compact model for circuit-level simulation derived.
- Phase-field models are being used to study and explain the experimental results in superconducting and 2-d FETs

[1] N. Pandey, Y. S. Chauhan, L. F. Register, and S. K. Banerjee, "2-D Analytical Modeling of the Magnetic Tunnel Junctions Including Multi-Domain Effects: Predictive Insights and Design Optimization," IEEE Transactions on Electron Devices, May 2024.

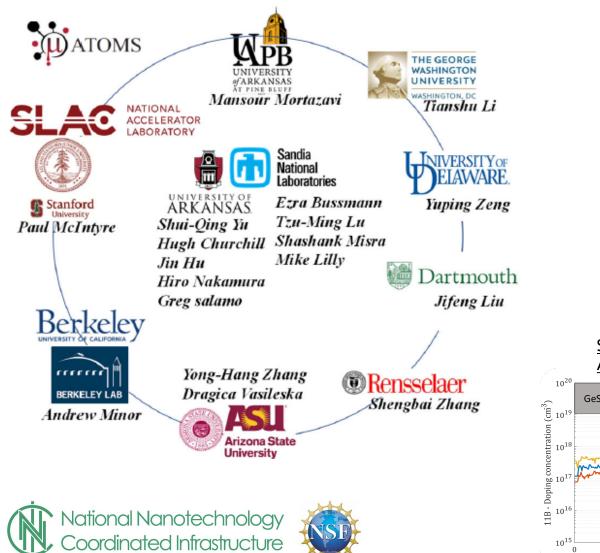
[2] N. Pandey, Y. S. Chauhan, L. F. Register, and S. K. Banerjee, "Impact of Multi-Domain Microscopic Interactions on Magnetic Tunnel Junction's Static and Transient Characteristics," 82nd Device Research Conference (DRC), Washington DC, USA, June 2024.



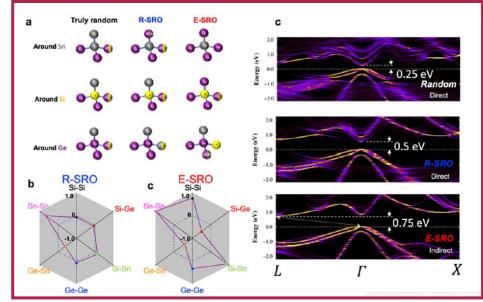




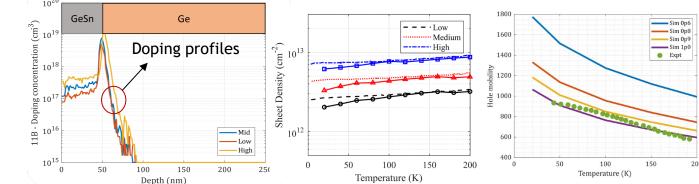
#### SiGeSn Material System (muATOMS EFRC)



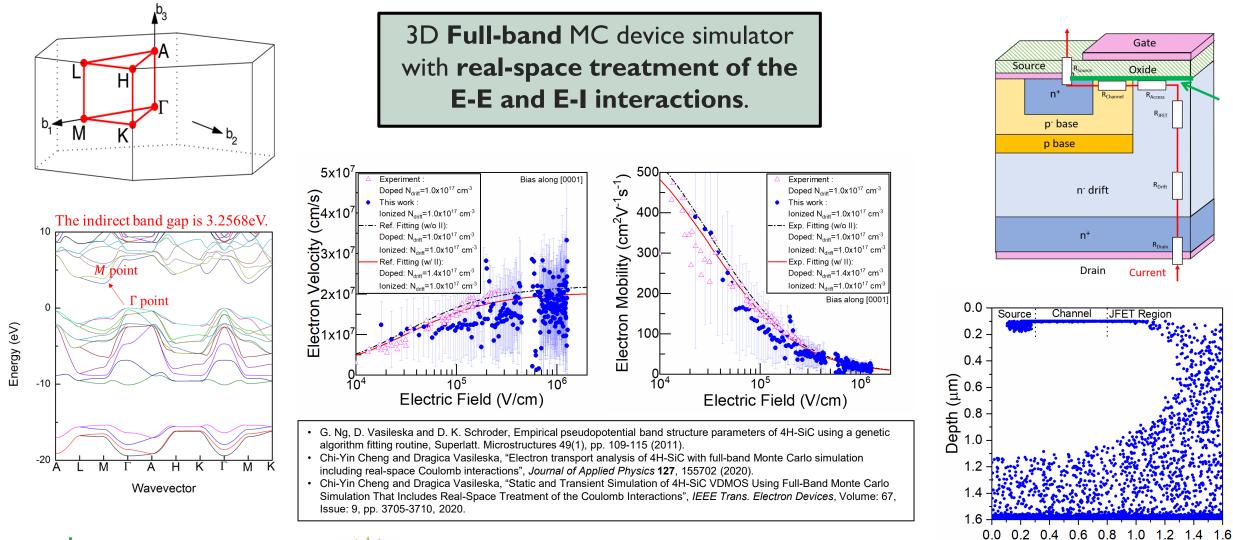
Short-Range Order: Another Degree of Freedom for Material Design



<u>Sandia National Lab</u>: Experimental characterization of GeSn/Ge heterostructures <u>Arizona State University</u>: Modeling of Hole transport in these heterostructures



#### Wide bandgap devices: Modeling of 4H SiC VDMOS



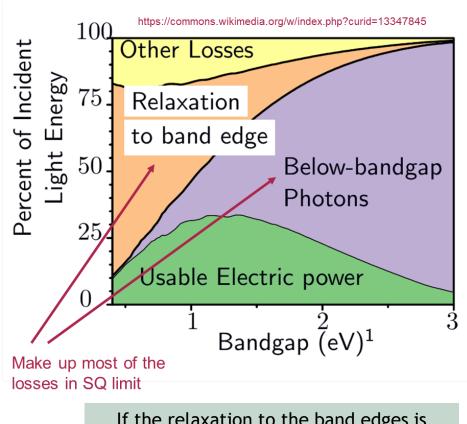






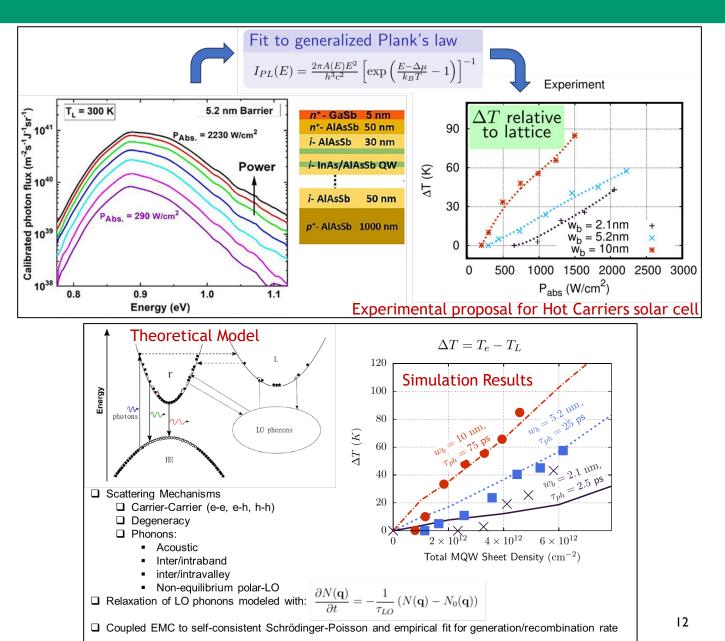
Length (µm)

### Modeling of Hot Carriers Solar Cells (S. M. Goodnick / D. Vasileska)

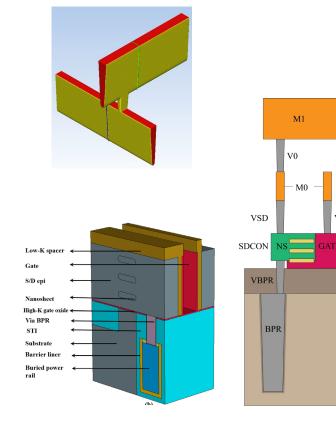


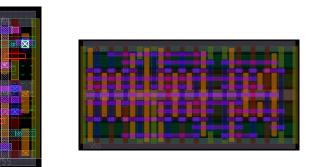
If the relaxation to the band edges is prevented, efficiency of the cell can be increased → HOT CARRIERS SOLAR CELL



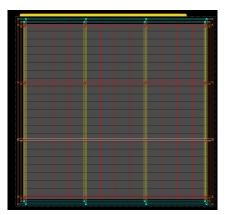


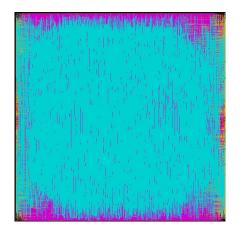
#### 3nm Nanosheet GAA-FET Process Design Kit





Standard Cell Library Design and Characterization (~ 60 cells)





Place and Route

Interconnect and Transistor TCAD and Process Simulations





BEOL Definition and Characterization



Semiconductor Research Corporation





#### Collaboration with Synopsys: Process Emulations

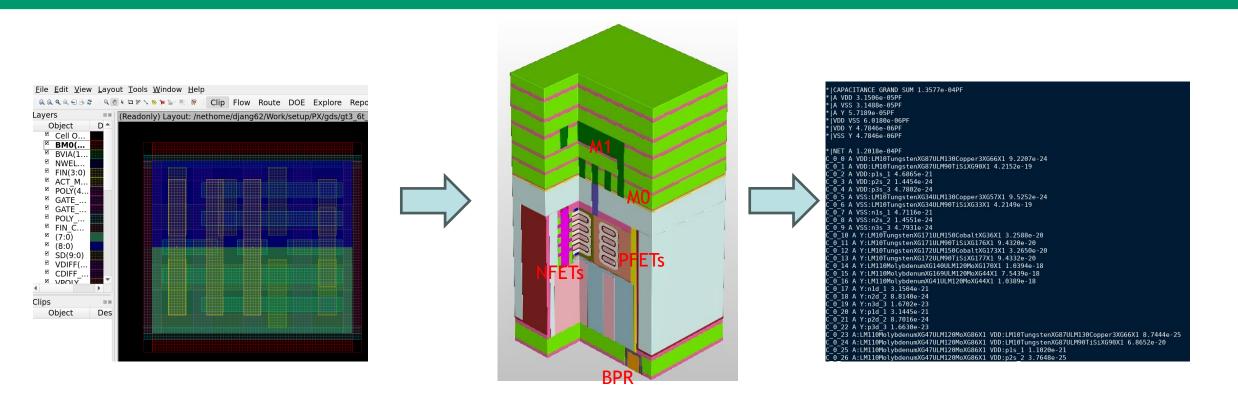
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m2Thickness	0.03 um			
nanosheetThickness	0.005 um			
numberOfNanosheets	4			
sdExtension	0.006 um			
substrateThickness	0.1 um			
tcThickness	0.02 um			
vdiffThickness	0.02 um			
via0Thickness	0.025 um			
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v etch strip resist				
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<ul> <li>v etch strip oxide3</li> </ul>				
depo iso oxideCVD spacer 20nm				

Collaboration with Drs. Victor Moroz, Alexei Svizhenko, and Joanne Huang from Synopsys





#### 3nm Nanosheet GAA-FET PDK Development



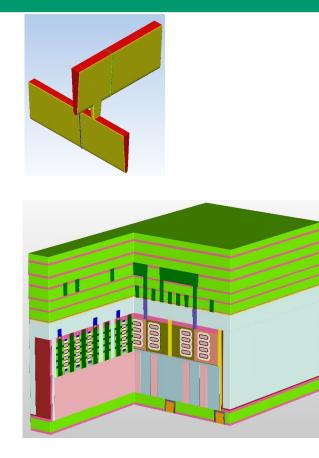
3nm GDS layout with appropriate layer assignments

Foundry 3nm fabrication process emulated by Process Explorer Raphael FX extracts overall parasitic RC netlist (.spf).



Process-aware cell library generation!

### DTCO: TCAD to Full Chip

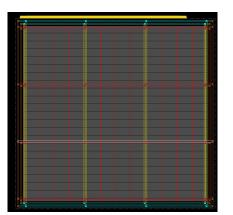


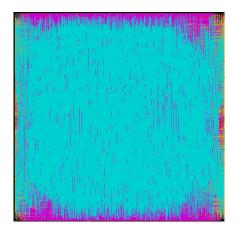
**Process Aware TCAD Simulations** 





Standard Cell Library Design and Characterization (~ 60 cells)





Place and Route

BEOL Definition and Characterization





- Short Course on Electronic Device Modeling
- Immersive Virtual Worlds for Experiential Learning of Microelectronics
- Physical modeling for FeFETs, MTJs, SiGeSn material systems, SiC VDMOS, and Hot Carrier Solar Cells.
- Open Source PDK for the 3nm nanosheet CMOS Technology



